PT100Mx0MP Series

■ Features

- 1. Compact and thin package
- 2. Surface mount type
- 3. 2-way mounting: top view/side view
- 4. Reflow soldering
- 5. Transparent resin: PT100MC0MP
- Visible light cut-off resin : PT100MF0MP
 Pair use with GL100MN0MP/GL100MN1MP
 is recommended

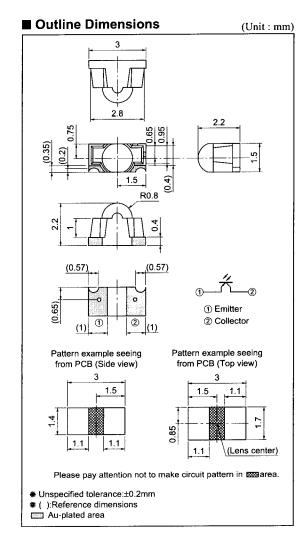
■ Applications

- 1. Touch panels for ATM
- 2. Touch panels for Car navigation system
- 3. Touch panels for FA equipment

■ Absolute Maximu	(T _a =25°C		
Parameter	Symbol	Rating	Unit
Collector-emitter voltage	V_{CEO}	35	V
Emitter-collector voltage	V _{ECO}	6	V
Collector current	$I_{\rm C}$	20	mA
Collector power dissipation	P_{C}	75	mW
Operating temperature	Topr	-30 to +85	°C
Storage temperature	T _{stg}	-40 to +95	°C
*1 Soldering temperature	T _{sol}	240	°C

^{*1} Max. 10s

Compact, Surface Mount Type Phototransistor



■ Electro-optical Cha	aracteristics	;				($T_a=25^{\circ}C$
Parameter		Symbol Conditions		MIN.	TYP.	MAX.	Unit
Collector current	PT100MC0MP	I_C * $E_e=1$ mW/cm ² , $V_{CE}=5$ V		1.7	2.9	5.1	mA
	PT100MF0MP	$l_{\rm C}$	* E _e =1mW/cm ² , V _{CE} =5V	1.15	2	3.45	mA
Collector dark current		I_{CEO}	E _e =0, V _{CE} =20V	T -	1.0	100	nA
Collector-emitter saturation voltage		V _{CE (sat)}	* E _e =10mW/cm ² , I _C =0.5mA	_	0.1	0.4	V
Collector-emitter breakdown voltage		BV_{CEO}	E _e =0, I _C =0.1mA	35	_	_	V
Emitter-collector breakdown voltage		BV _{ECO}	E _e =0, I _E =0.01mA	6	_	-	V
Peak sensitivity wavelength	PT100MC0MP	λ	_	_	900		nm
	PT100MF0MP	$\lambda_{\rm p}$	-	_	910		nm
Response time	Rise time	t _r	$V_{CE}=2V$, $I_{C}=2mA$, $R_{L}=100\Omega$	_	5.0	_	μs
	Fall time	tr	$V_{CE}=2V$, $I_{C}=2mA$, $R_{L}=100\Omega$		6.0		μs
Half intensity angle		Δθ	_	_	±15	-	۰

^{*} E_e:Irradiance by CIE standard light source A (tungsten lamp)

Fig.1 Collector Power Dissipation vs.

Ambient Temperature

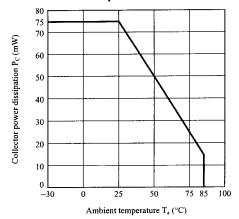


Fig.3 Relative Collector Current vs. Ambient

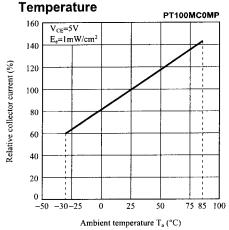


Fig.2 Collector Dark Current vs. Ambient Temperature

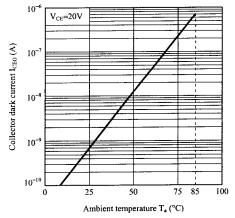
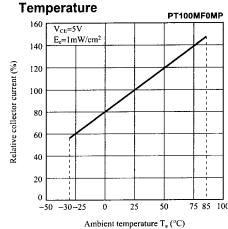


Fig.4 Relative Collector Current vs. Ambient



PT100Mx0MP Series

Fig.5 Collector Current vs. Irradiance

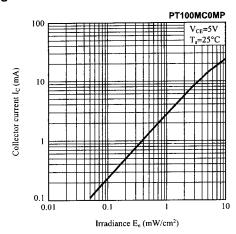


Fig.7 Collector Current vs. Collector-emitter Voltage

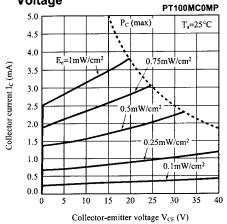


Fig.9 Relative Sensitivity vs. Wavelength

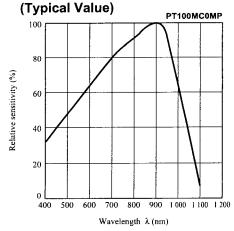


Fig.6 Collector Current vs. Irradiance

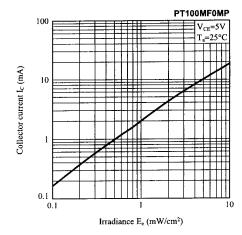


Fig.8 Collector Current vs. Collector-emitter Voltage

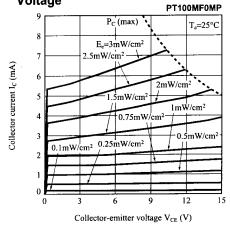


Fig.10 Relative Sensitivity vs. Wavelength

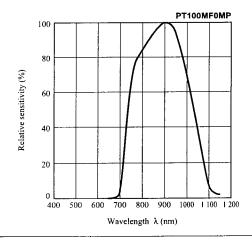
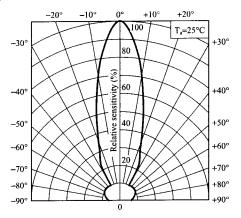


Fig.11 Radiation Diagram



Angular displacement θ

Fig.12 Collector-emitter Saturation Voltage

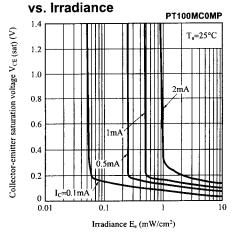


Fig.14 Relative Output vs. Distance To Detector

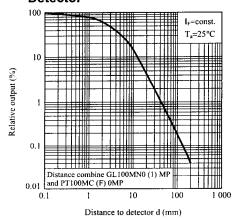


Fig.13 Collector-emitter Saturation Voltage

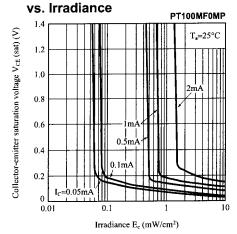
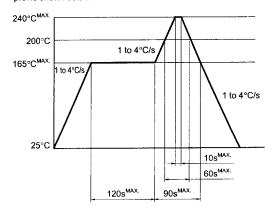


Fig.15 Reflow Soldering

Only one time soldering is recommended within the temperature profile shown below.

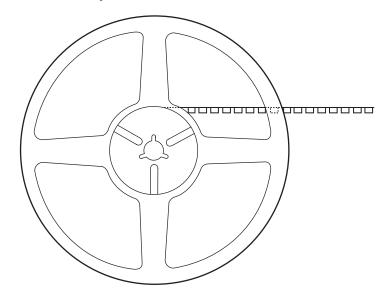


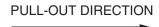
NOTICE

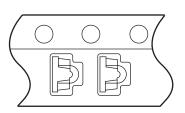
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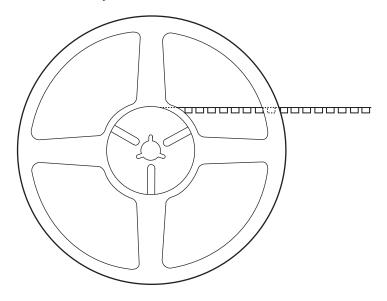








GL100xxxxP1 PD100xxxxP1 PT100xxxxP1 1,500 Pieces per reel



PULL-OUT DIRECTION

